

SLD18P10G

-100V P -Channel MOSFET

General Description

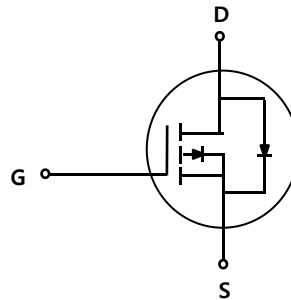
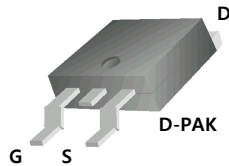
This Power MOSFET is produced using Maple semi's advanced Split gate trench MOSFET technology. This advanced technology has been especially tailored to minimize conduction loss, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

Application

- Portable equipment
- Load Switch
- Power Management

Features

- P-Channel: -100V -18A
- $R_{DS(on)Typ} = 90m\Omega @ V_{GS} = -10V$
- $R_{DS(on)Typ} = 100m\Omega @ V_{GS} = -4.5V$
- Very Low On-resistance RDS(ON)
- LowCrss
- Fast switching
- 100% avalanche tested
- Excellent stability and uniformity



Absolute Maximum Ratings

$T_C = 25^\circ C$ unless otherwise noted

Symbol	Parameter	SLD18P10G	Units
V_{DSS}	Drain-Source Voltage	-100	V
I_D	Drain Current - Continuous ($T_C = 25^\circ C$)	-18	A
	- Continuous ($T_C = 100^\circ C$)	-12	A
I_{DM}	Drain Current - Pulsed (Note 1)	-72	A
V_{GSS}	Gate-Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy	100	mJ
P_D	Power Dissipation ($T_C = 25^\circ C$)	70	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.75	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	105	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ C$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ C$

* Drain current limited by maximum junction temperature.

Package Marking

Part Number	Top Marking	Package	Packing Method	MOQ	QTY
SLD18P10G	SLD18P10G	D-Pak	Tape & Reel	5000	25000

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	-100	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}$	--	--	-1	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$	--	--	-1	μA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -20\text{ V}, V_{DS} = 0\text{ V}$	--	--	1	μA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	-1.0	-1.8	-2.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -10\text{ V}, I_D = -10\text{ A}$	--	90	110	$\text{m}\Omega$
		$V_{GS} = -4.5\text{ V}, I_D = -5\text{ A}$	--	100	130	$\text{m}\Omega$

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = -25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	1050	-	pF
C_{oss}	Output Capacitance		--	97	-	pF
C_{rss}	Reverse Transfer Capacitance		--	18	-	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{GS} = -10\text{ V}, V_{DS} = -50\text{ V},$ $R_G = 2.5\text{ }\Omega, I_D = -5\text{ A}$	--	10	--	ns
t_r	Turn-On Rise Time		--	3	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	77	--	ns
t_f	Turn-Off Fall Time		--	81	--	ns
Q_g	Total Gate Charge	$V_{DS} = -50\text{ V}, I_D = -5\text{ A},$ $V_{GS} = -10\text{ V}$	--	20	--	nC
Q_{gs}	Gate-Source Charge		--	3.9	--	nC
Q_{gd}	Gate-Drain Charge		--	4.3	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	-18	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	72	A
V_{SD}	Drain to Source Diode Forward Voltage, $V_{GS} = 0\text{ V}, I_{SD} = -10\text{ A}, T_J = 25^\circ\text{C}$	--	--	-1.5	V

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition : $T_J = 25^\circ\text{C}, V_{DD} = -50\text{ V}, V_G = 10\text{ V}, L = 0.5\text{ mH}, R_G = 25\text{ }\Omega,$
3. Pulse Test: Pulse Widths $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 0.5\%$

N- Channel Typical Characteristics

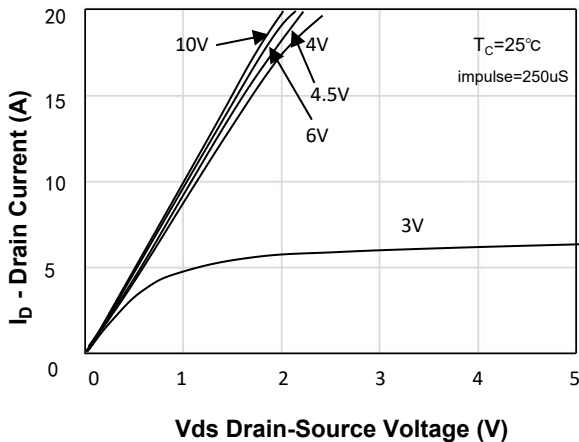


Figure 1. On-Region Characteristics

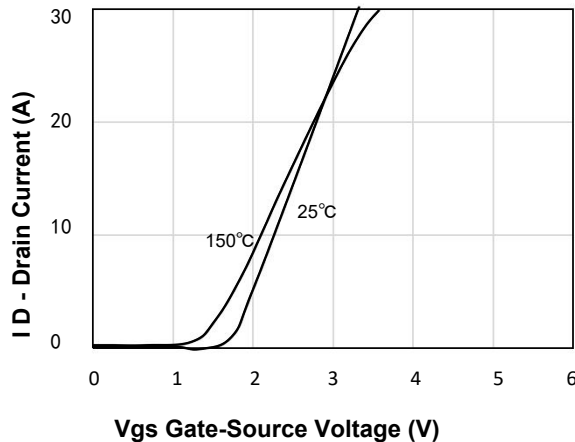


Figure 2. Transfer Characteristics

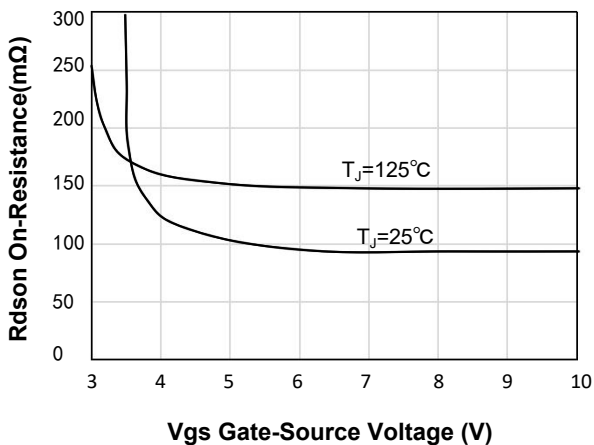


Figure 3. On-Resistance Variation vs Gate Voltage

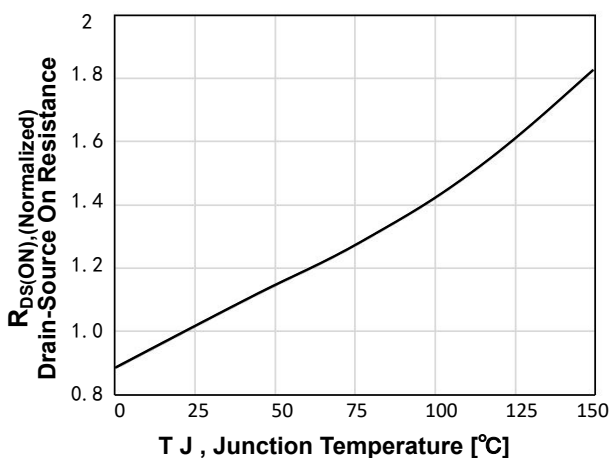


Figure 4. On-Resistance Variation vs Temperature

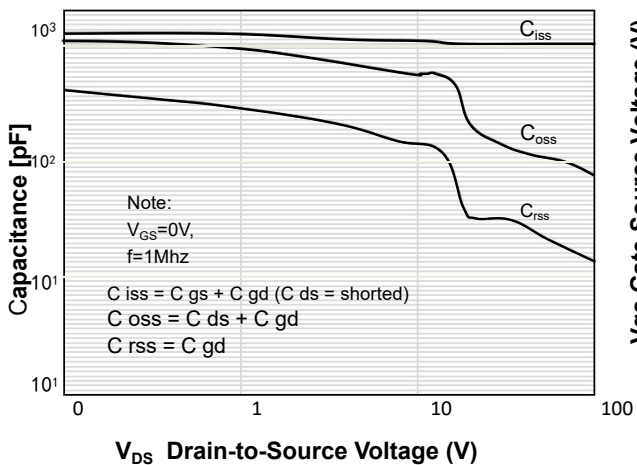


Figure 5. Capacitance Characteristics

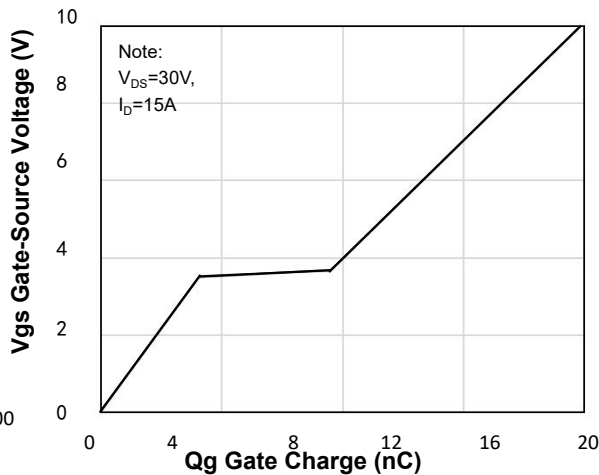


Figure 6. Gate Charge Characteristics

N- Channel Typical Characteristics (Continued)

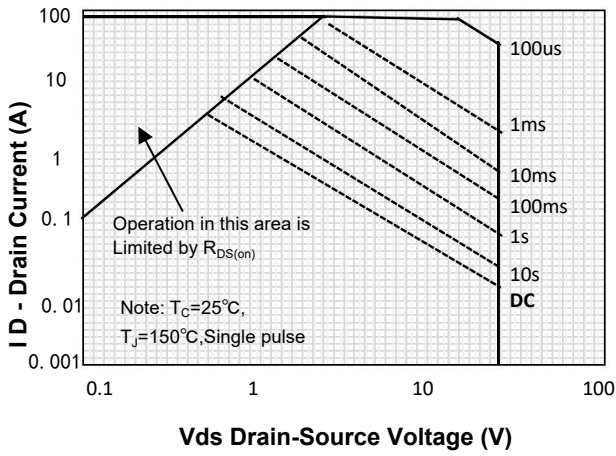


Figure 7. Maximum Safe Operating Area

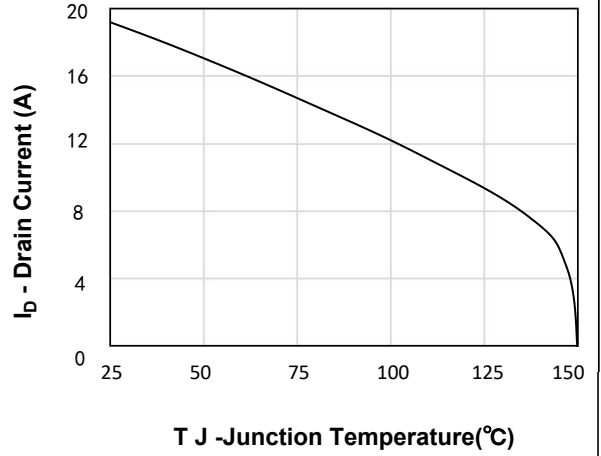
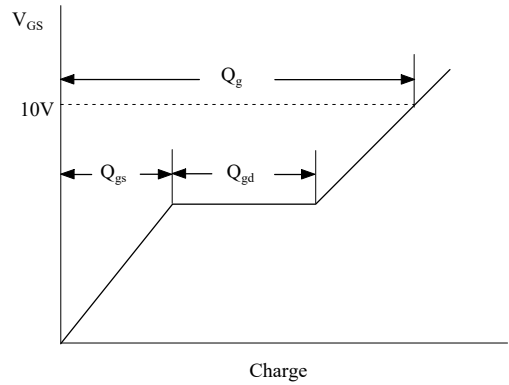
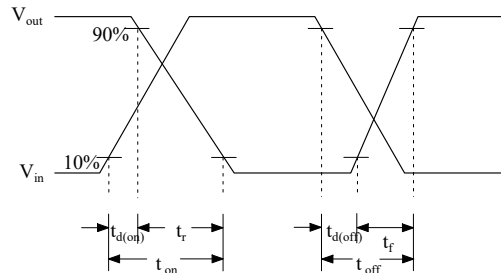
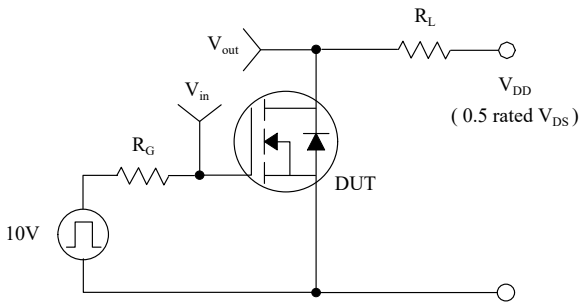


Figure 8. Maximum PContinuous Drain Current vs Case Temperature

Gate Charge Test Circuit & Waveform



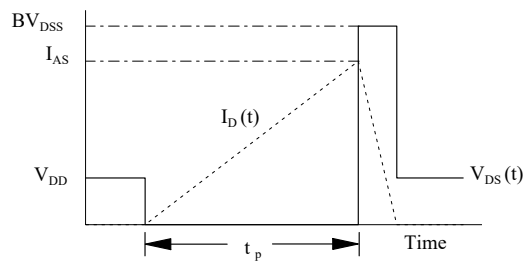
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



$$E_{AS} = \frac{1}{2} L_L I_{AS}^2$$



Peak Diode Recovery dv/dt Test Circuit & Waveforms

